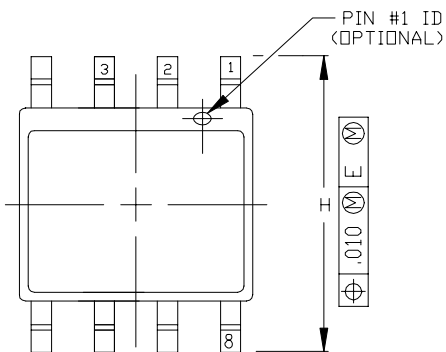
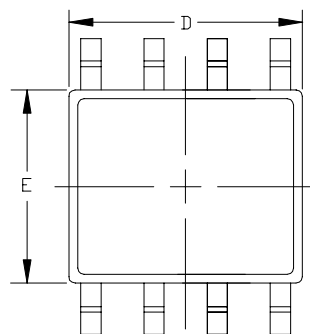


SOIC and TSOP Packages - S08, V08

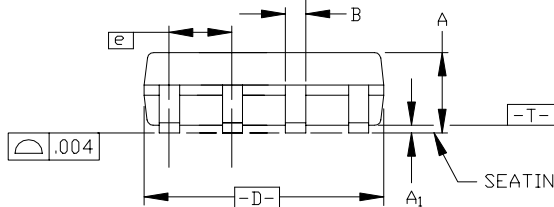
TOP VIEW



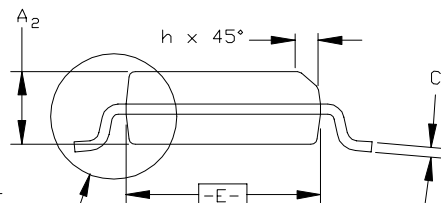
BOTTOM VIEW



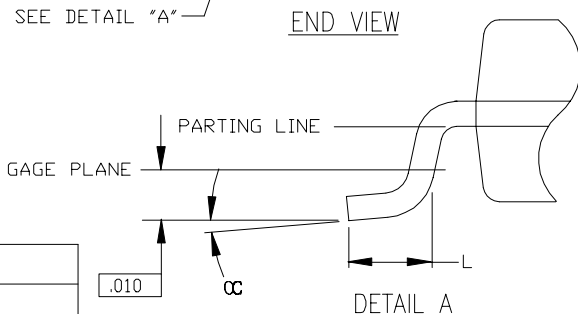
⊕ .010 (M) T E (M) D S



SIDE VIEW



END VIEW



SYMBOL	S08			V08		
	INCHES			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	.059	.064	.068	<i>h</i>	<i>h</i>	.047
A ₁	.004	.006	.0098	.002	.004	.006
A ₂	.055	.058	.061	.037	.039	.044
B	.013	.016	.020	.0138	<i>h</i>	.0192
C	.0075	.008	.0098	.0075	<i>h</i>	.0089
D	.189	.194	.196	.189	.194	.196
E	.150	.155	.157	.150	.155	.157
e	.050 BSC			.050 BSC		
H	.229	.236	.244	.230	.236	.244
h	.010	.013	.019	.010	.013	.019
L	.016	.025	.035	.016	.025	.035
α	0°	5°	8°	0°	<i>h</i>	8°
REF.	JEDEC MS-012			<i>h</i>		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
2. DIMENSION 'D' DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
3. DIMENSION 'E' DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .010 INCH PER SIDE.
4. LEAD FINISH: SOLDER PLATE